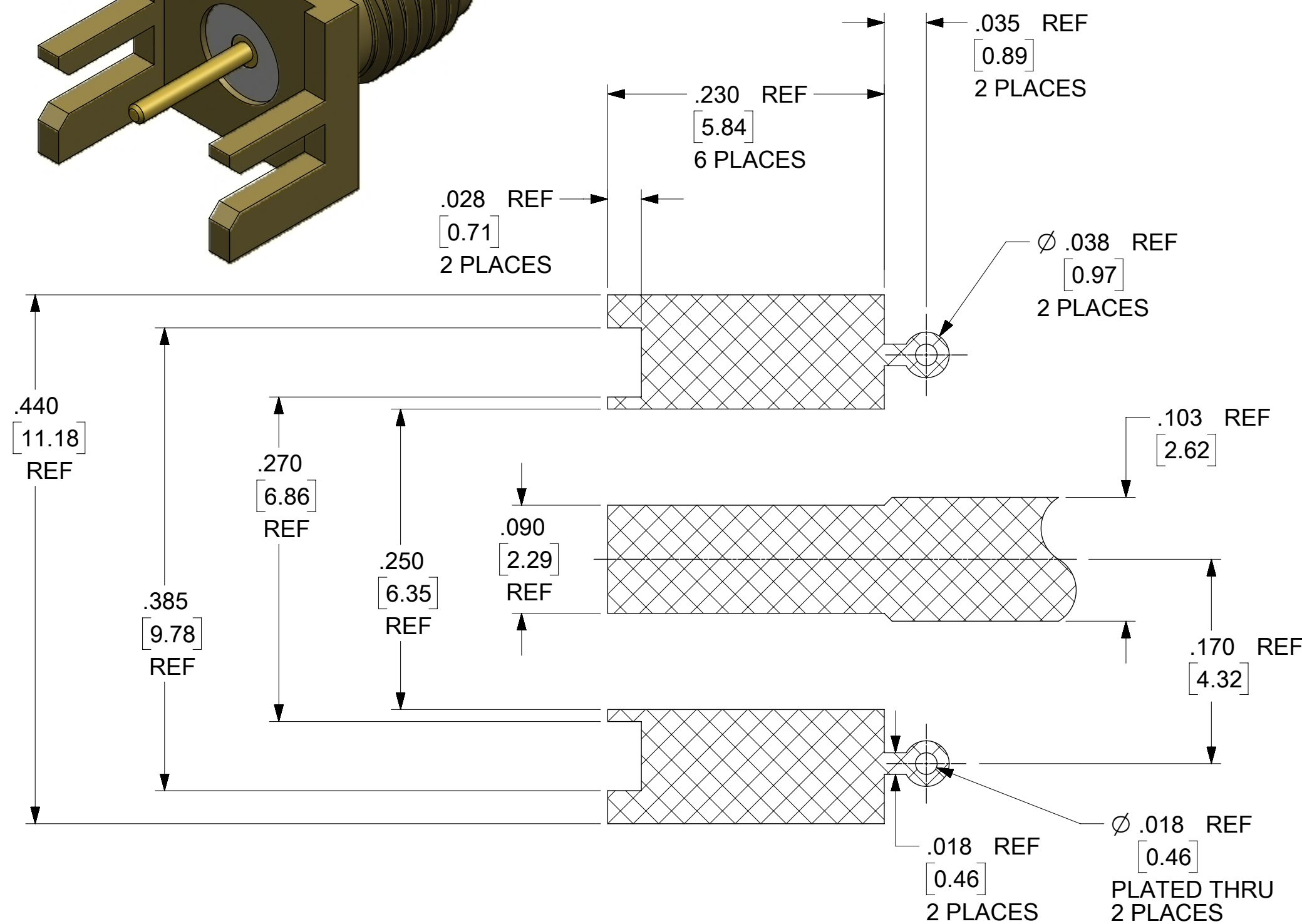
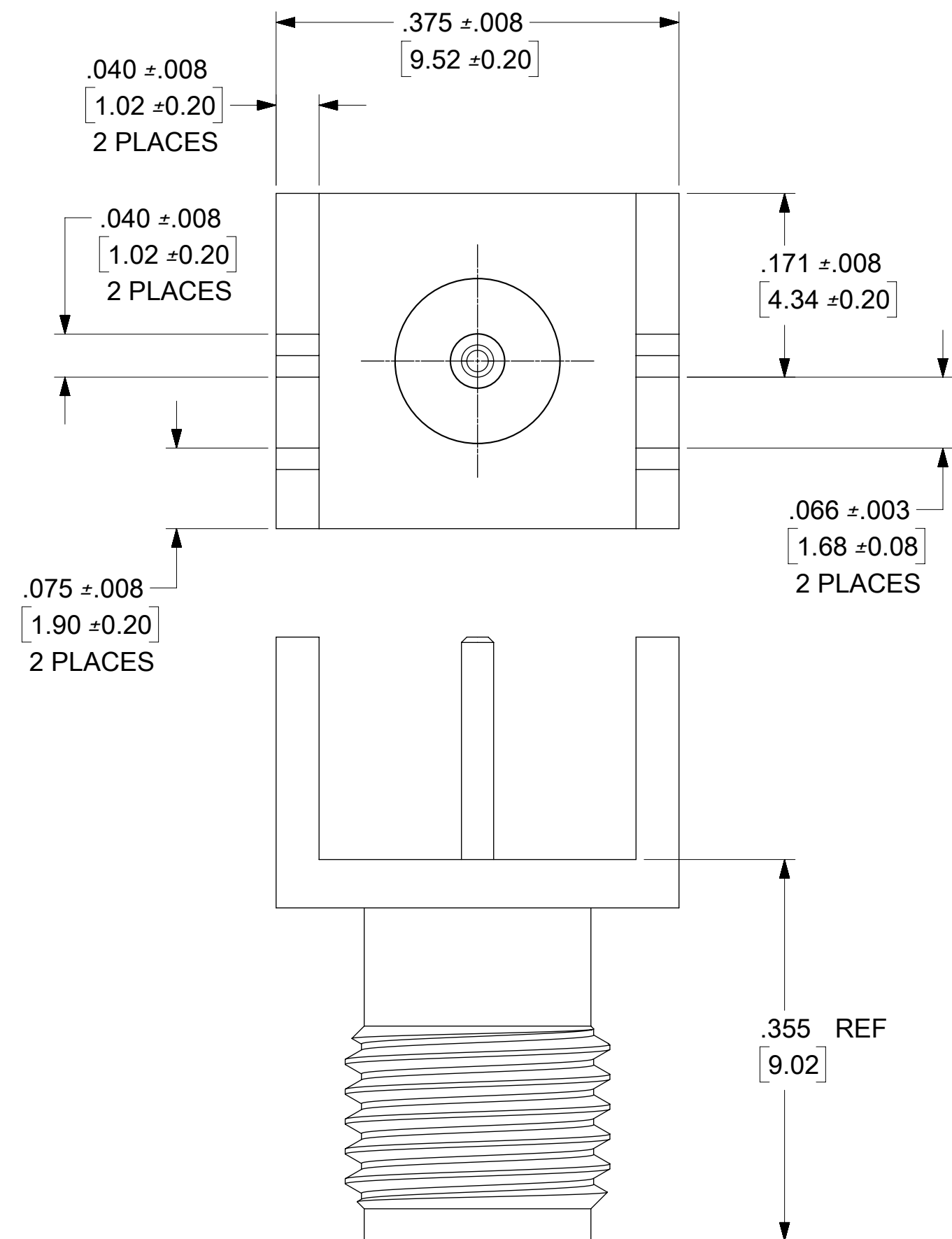
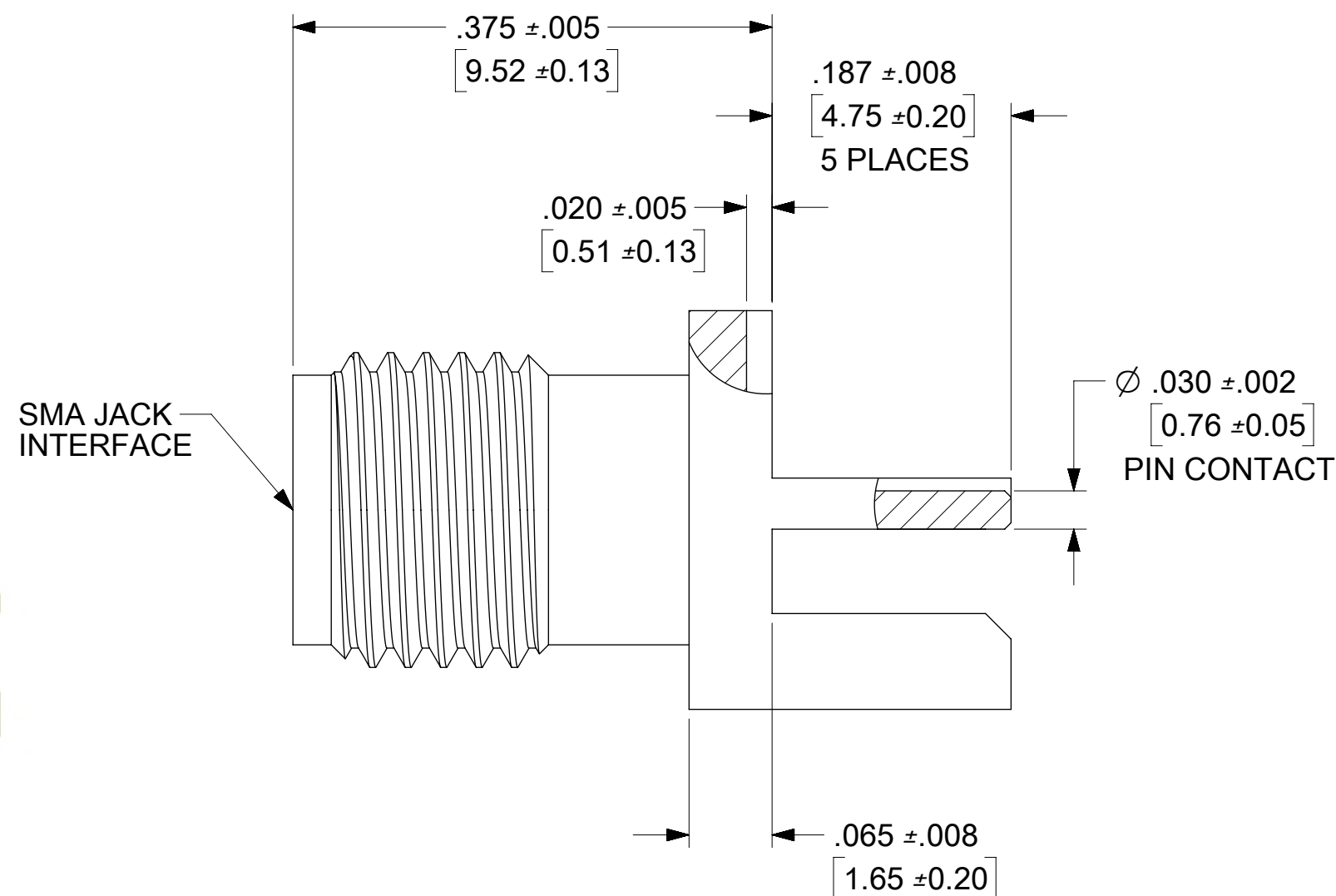
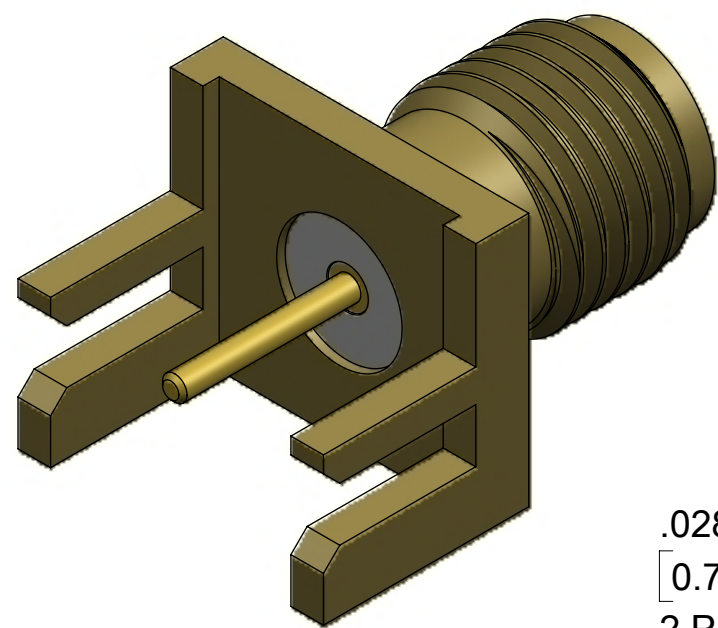
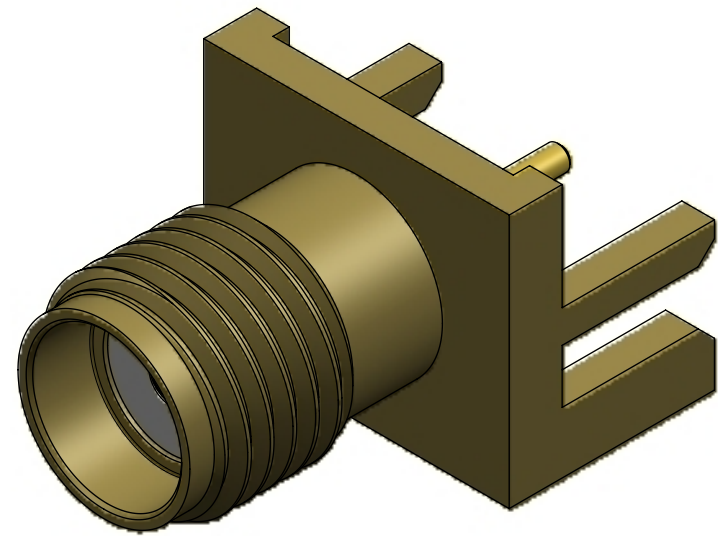


INSULATOR: PTFE



BOARD THICKNESS: .062 [1.57]
BOARD MATERIAL: FR4 WITH 1.0 OZ (28 g) COPPER
ON BOTTOM (GROUND) SIDE

73251-1153	GOLD (1μ-in MIN) OVER NICKEL (50μ-in MIN)	GOLD (5μ-in MIN) OVER NICKEL (50μ-in MIN)	TRAY (80 PIECES)
73251-1152	GOLD (10μ-in MIN) OVER NICKEL (50μ-in MIN)	GOLD (10μ-in MIN) OVER NICKEL (100μ-in MIN)	TRAY (20 PIECES)
73251-1151	GOLD (10μ-in MIN) OVER NICKEL (50μ-in MIN)	GOLD (10μ-in MIN) OVER NICKEL (100μ-in MIN)	ONE 73251-1150 PER BAG
73251-1150	GOLD (10μ-in MIN) OVER NICKEL (50μ-in MIN)	GOLD (10μ-in MIN) OVER NICKEL (100μ-in MIN)	TRAY (80 PIECES)
PART NO.	BODY	CONTACT	DESCRIPTION
	PLATING		PACKAGING

SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION													
 = 0	DIMENSION UNITS	SCALE		CURRENT REV DESC: SEE ECM			molex							
	INCH	NTS												
 = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)			SMA JACK, EDGE MOUNT 50 OHMS, EWR-11795 SMA-J/PCB										
 = 0														
	MM	INCH	PRODUCT CUSTOMER DRAWING											
 = 0	4 PLACES	±								±				
 = 0	3 PLACES	±							± 0.005					
 = 0	2 PLACES	± 0.13	± 0.01	EC NO: 172847			2018/02/23							
	1 PLACE	± 0.25	±	DRWN: LMEIER										
 = 0	0 PLACES	±	±	CHK'D: SSSHAH			2018/03/01							
	ANGULAR TOL	± 2.0 °		APPR: AROBERTSON										
 = 0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			INITIAL REVISION:			2002/06/27							
 = 0				DRWN: TEF										
				APPR: GMH			2002/06/27							
		THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER		
		 		C-SIZE		73251		SEE TABLE				1 OF 1		